

# DIP TYPE

## STA

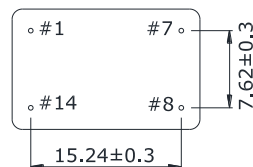
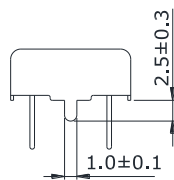
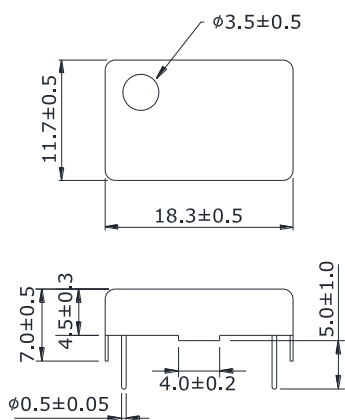
- Temperature Compensated Crystal Oscillator
- CMOS / TTL Output
- Clipped Sinewave Output
- 3.3 V, 5.0 V Supply Voltage



### ELECTRICAL SPECIFICATIONS

ITEM	Value	
Output Logic Type	Clipped Sinewave	CMOS
Frequency Range	6.000 MHz to 190.000 MHz	1.000 kHz to 800.000 MHz
Supply Voltage(V <sub>DD</sub> )	3.3 V <sub>DC</sub> ± 5 %, 5.0 V <sub>DC</sub> ± 5 %	3.3 V <sub>DC</sub> ± 5 %, 5.0 V <sub>DC</sub> ± 5 %
Operating Temperature Range	-40 to +85 °C	-40 to +85 °C
Storage Temperature Range	-40 to +85 °C	-40 to +85 °C
Frequency Stability		
Vs. Temperature	±0.5 ppm to ±5.0 ppm Max.	±0.5 ppm to ±5.0 ppm Max.
Vs. Supply voltage (±5 %)	±0.3 ppm Max.	±0.3 ppm Max.
Vs. Load (±10 %)	±0.3 ppm Max.	±0.3 ppm Max.
Vs. Aging	±1.0 ppm Max. / year	±1.0 ppm Max. / year
Frequency Tolerance	±1.0 ppm Max.	±1.0 ppm Max.
Input Current	2 mA to 30 mA Max.	15 mA to 100 mA Max.
Frequency Deviation	±5.0 ppm, ±10 ppm Min.	±5.0 ppm, ±10 ppm Min.
Control Voltage(V <sub>c</sub> )	1.65 V ± 1.5 V (V <sub>DD</sub> : 3.3 V) 2.5 V ± 2.0 V (V <sub>DD</sub> : 5.0 V)	1.65 V ± 1.5 V (V <sub>DD</sub> : 3.3 V) 2.5 V ± 2.0 V (V <sub>DD</sub> : 5.0 V)
Frequency Adjustment	±3.0 ppm Min. by internal Trimmer	±3.0 ppm Min. by internal Trimmer
Output Level		CMOS                      TTL
	0.8 V <sub>p-p</sub> Min. (V <sub>DD</sub> : 3.3 V)	90 % of V <sub>DD</sub> Min.      2.4 V <sub>DC</sub> Min.
	1.0 V <sub>p-p</sub> Min. (V <sub>DD</sub> : 5.0 V)	10 % of V <sub>DD</sub> Max      0.4 V <sub>DC</sub> Max.
Output Load Condition	10 kΩ//10 pF	15 pF or 10 TTL
Phase Noise at 1kHz offset	-135 dBc/Hz	-135 dBc/Hz

### MECHANICAL DIMENSIONS (mm)



CONNECTION  
 #1 : V.C or N.C  
 #7 : GND  
 #8 : OUTPUT  
 #14: V<sub>DD</sub>

**PART NUMBERING GUIDE**

**STA 33 20 H S 5 - 10.000M**

**SUPPLY VOLTAGE(V<sub>DD</sub>)**

50 : 5.0 V  
33 : 3.3 V

**FREQUENCY STABILITY**

TABLE 1

**OPERATING TEMPERATURE RANGE**

TABLE 1

**OUTPUT**

M : HCMOS  
S : CLIPPED SINEWAVE

**FREQUENCY**

M : MHz

**FREQUENCY DEVIATION**

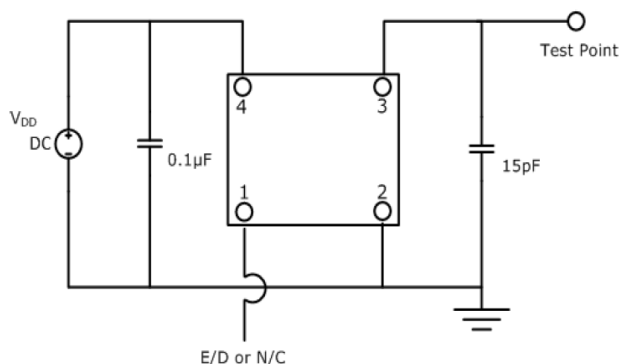
BLANK : TCXO  
5 : ± 5 ppm min.  
10 : ± 10 ppm min.

**TABLE 1**

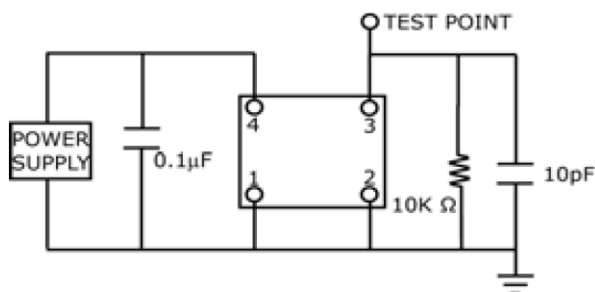
**FREQUENCY STABILITY VS. TEMPERATURE RANGE**

Temp	Stability	±0.5	±1.0	±1.5	±2.0	±3.0	±5.0
		05	10	15	20	30	50
0~50°C	A	*	*	*	*	*	*
-10~60°C	B	*	*	*	*	*	*
-10~70°C	C	*	*	*	*	*	*
-20~70°C	D	*	*	*	*	*	*
-30~60°C	E	*	*	*	*	*	*
-30~70°C	F	*	*	*	*	*	*
-30~75°C	G	*	*	*	*	*	*
-40~80°C	H		*	*	*	*	*
-40~85°C	I		*	*	*	*	*

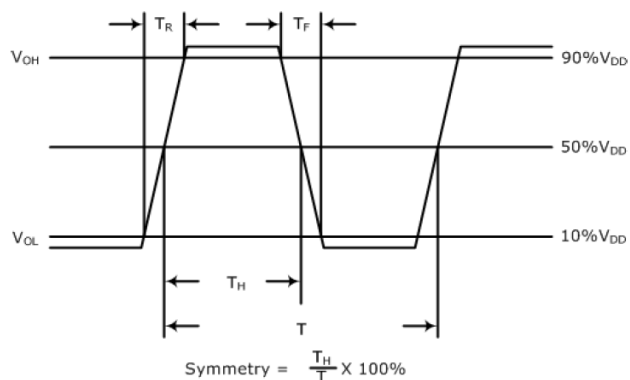
**TEST CIRCUIT (CMOS)**



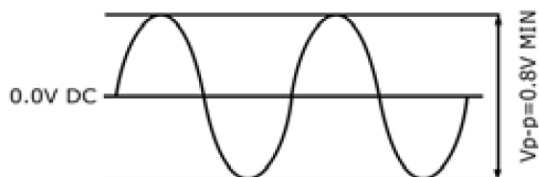
**TEST CIRCUIT (Clipped Sinewave)**



**WAVEFORM (CMOS)**

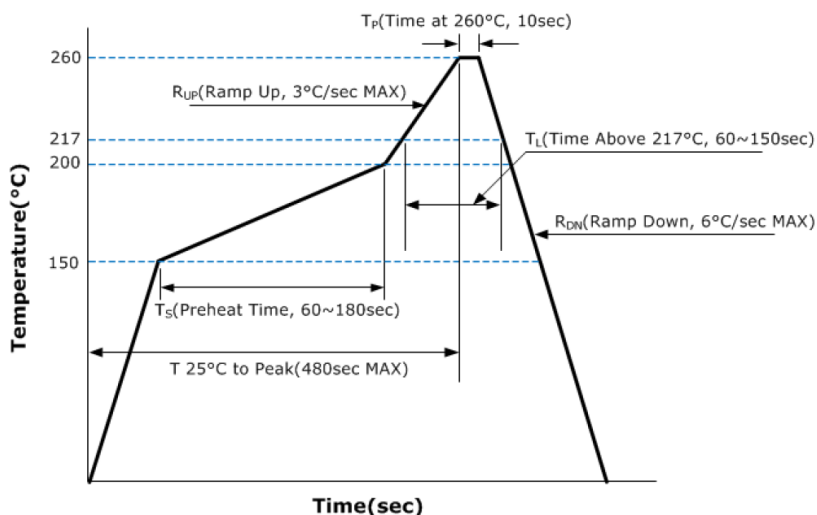


**WAVEFORM (Clipped Sinewave)**



**REFLOW PROFILE**

**MARKING GUIDE**



Frequency in MHz  
 Model Name

**LINE 1 : STA25DM**  
**LINE 2 : XX.XXX MHz**  
**LINE 3 : YY.MM**  
**LINE 4 : SUNNY**

Year  
 Month

**ENVIRONMENTAL & MECHANICAL SPECIFICATIONS**

Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Vibration	MIL-STD-883, Method 2007, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Solderability	MIL-STD-883, Method 2003